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SPC-F005.DWG

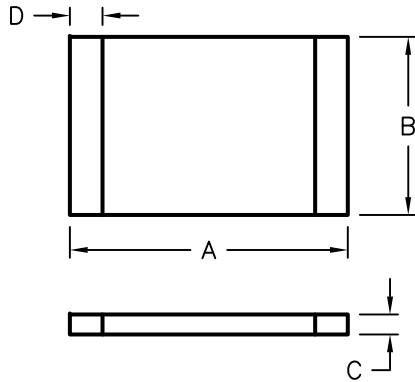
REVISIONS

DOC. NO. SPC-F005 * Effective: 7/8/02 * DCP No: 1398

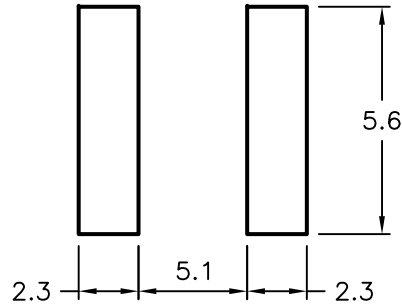
DCP #	REV	DESCRIPTION	DRAWN	DATE	CHECKD	DATE	APPRVD	DATE
2063	A	RELEASED	JN	08/04/09	JWM	08/06/09	JWM	08/06/09



Dimensions



Pad Layout



SPECIFICATION

1. Lead Material: Pure Tin
2. Soldering characteristic: Meets EIA specs. RS 186-9E, ANSI/J-std-002 Category 3
3. Operating Current: 300mA~3.0A
4. Maximum Voltage: 6V~60V
5. Temperature Range: -40°C to 85°C

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (T _{smax} to T _p)	3 C/second max.
Preheat :	
Temperature Min (T _{smin})	150 C
Temperature Max (T _{smax})	200 C
Time (t _{smin} to t _{smax})	60-180 seconds
Time maintained above: Temperature(I)	217 C
Time (t _L)	60-150 seconds
Peak/Classification Temperature(T _p)	260 C
Time within 5C of actual Peak :	
Temperature (tp)	20-40 seconds
Ramp-Down Rate :	6 C /second max.
Time 25C to Peak Temperature :	8 minutes max.

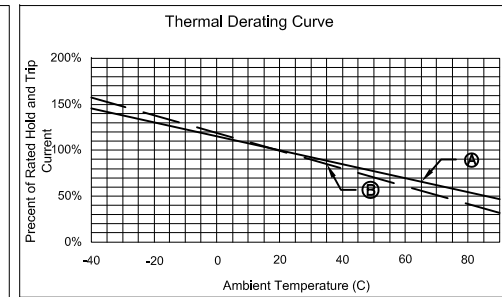
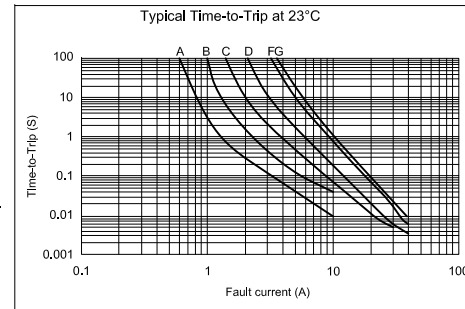
Solder reflow

*Due to "Lead Free" nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.

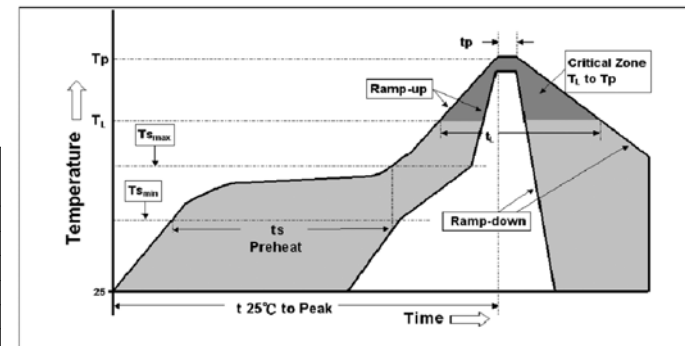
1. Recommended max past thickness > 0.25mm.
2. Devices can be cleaned using standard methods and aqueous solvent.
3. Rework use standard industry practices.
4. Storage Environment : < 30°C / 60%RH

Caution:

1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
2. Devices are not designed to be wave soldered to the bottom side of the board.



Mfg. P/N	A		B		C		D	Hold Current	Trip Current	Rated Voltage	Maximum Current	Typical Power	Max Time-to-Trip		Resistance Tolerance		Time-to-Trip Curve Option	Thermal Derating Curve Option
	Min	Max	Min	Max	Min	Max	Min	I _H , A	I _T , A	V _{MAX} , Vdc	I _{MAX} , A	Pd, W	Current	Time	R _{MIN} ohms	R _{1MAX} ohms		
MC33189	6.73	7.98	4.8	5.44	0.6	1.15	0.35	0.3	0.6	60	10	1.5	1.5	3	1	4.8	Option A	Option A
MC33192	6.73	7.98	4.8	5.44	0.6	1.15	0.35	0.5	1	60	10	1.5	2.5	4	0.3	1.4	Option B	Option A
MC33194	6.73	7.98	4.8	5.44	0.35	1.15	0.35	0.75	1.5	33	40	1.5	8	0.3	0.18	1	Option C	Option A
MC33195	6.73	7.98	4.8	5.44	0.4	1	0.35	1.1	2.2	33	40	1.5	8	0.5	0.09	0.41	Option D	Option A
MC33197	6.73	7.98	4.8	5.44	0.4	0.9	0.35	1.5	3	33	40	1.5	8	2	0.05	0.23	Option F	Option B
MC33198	6.73	7.98	4.8	5.44	0.3	0.9	0.35	1.85	3.7	33	40	1.5	8	2.5	0.04	0.15	Option G	Option B



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TOLERANCES: UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE FOR REFERENCE PURPOSES ONLY.

DRAWN BY: Jason Nash
 CHECKED BY: JWM
 APPROVED BY: JWM
 DATE: 08/06/09
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 DATE: 08/06/09

DRAWING TITLE: Surface Mountable PTC Resettable Fuse
 SIZE: A
 DWG. NO.: Ta-1191
 ELECTRONIC FILE: Ta-1191.dwg
 REV: A
 SCALE: NTS
 U.O.M.: INCHES [mm]
 SHEET: 1 OF 1